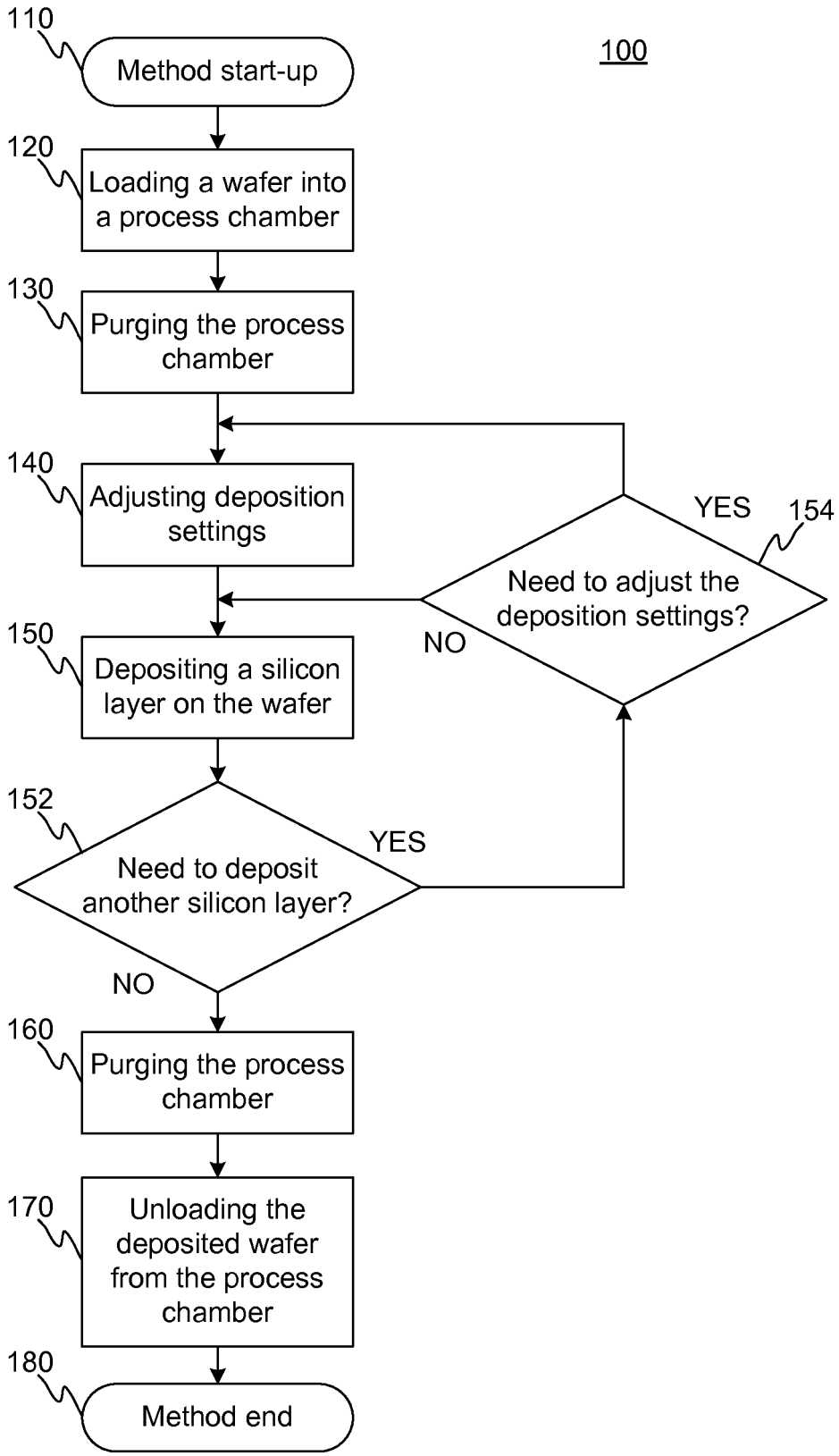

100
110
Method start-up
120
Loading a wafer into a process chamber
130
Purging the process chamber
140
Adjusting deposition settings
150
Depositing a silicon layer on the wafer
152
Need to deposit another silicon layer?
YES
NO
154
Need to adjust the deposition settings?
YES
NO
160
Purging the process chamber
170
Unloading the deposited wafer from the process chamber
180
Method end

Figure 1

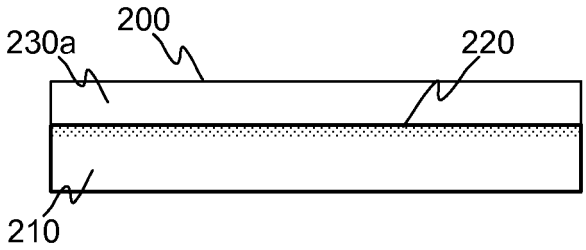


Figure 2a

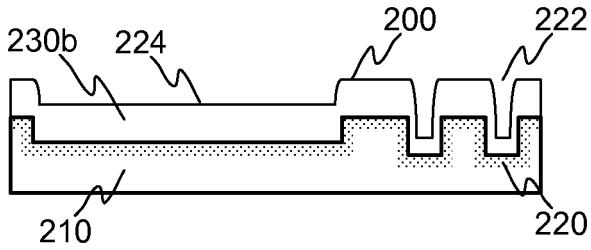


Figure 2b

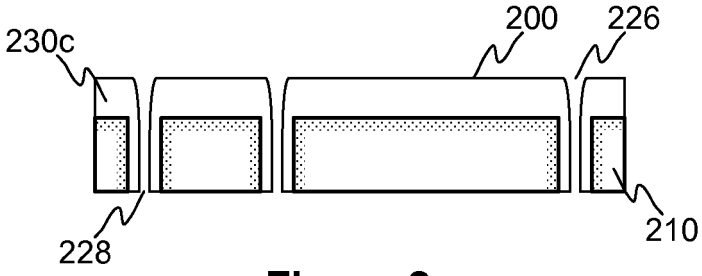


Figure 2c

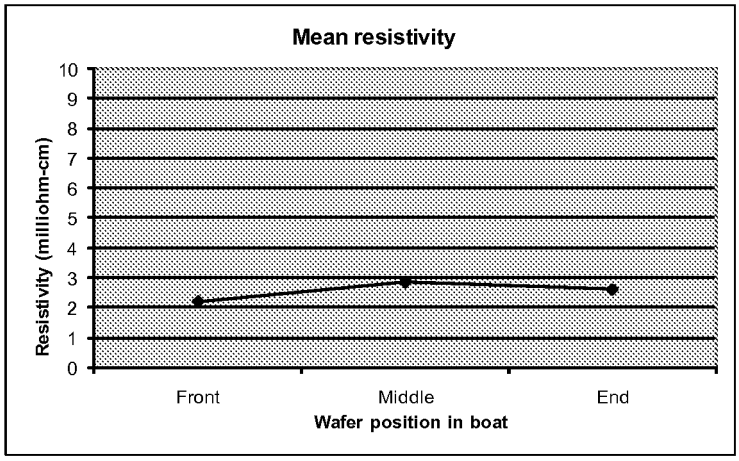


Figure 3a

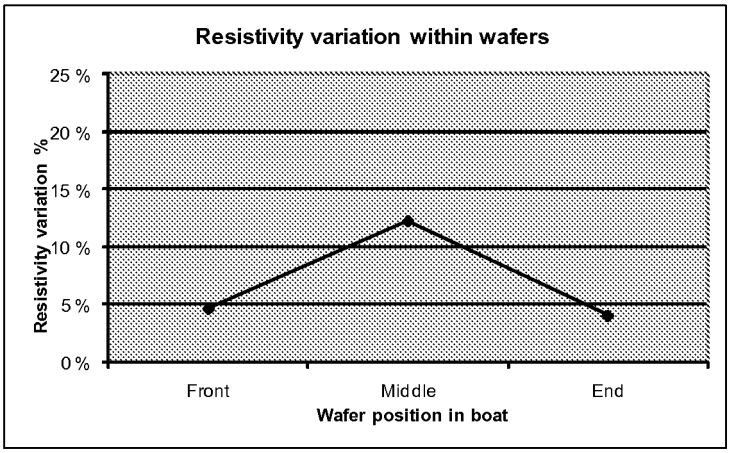


Figure 3b

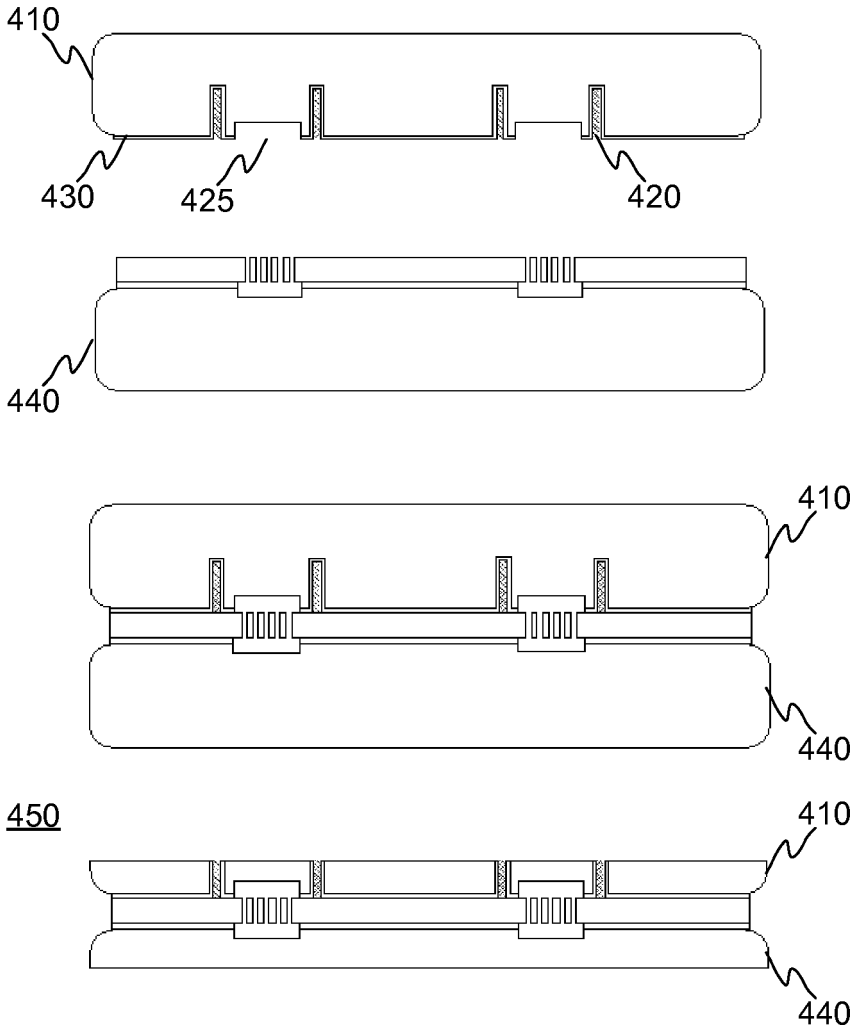


Figure 4

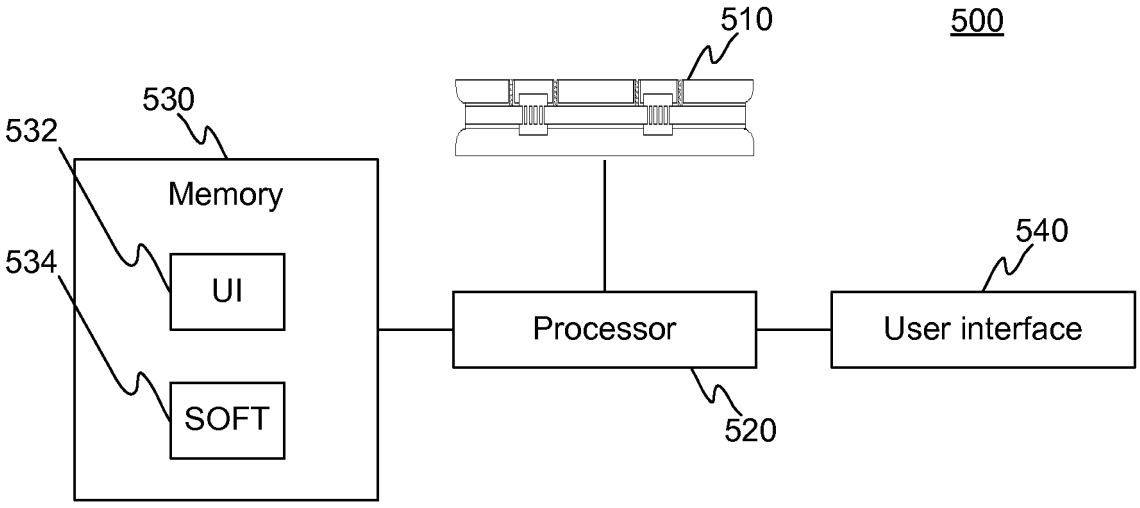


Figure 5